

### Material Features:

- Low pressure capabilities
- Low thermal resistance
- Good thermal stability

### Applications

- Graphic Processors
- Base stations
- Microprocessors
- Laptops, CPU/APUs

### Storage Conditions:

- Store in dark environment
- Storage Temperature:  $\leq 30^{\circ}\text{C}$
- Storage Humidity:  $\leq 70\%$

### Shelf Life:

- Stored at storage conditions:  
one year

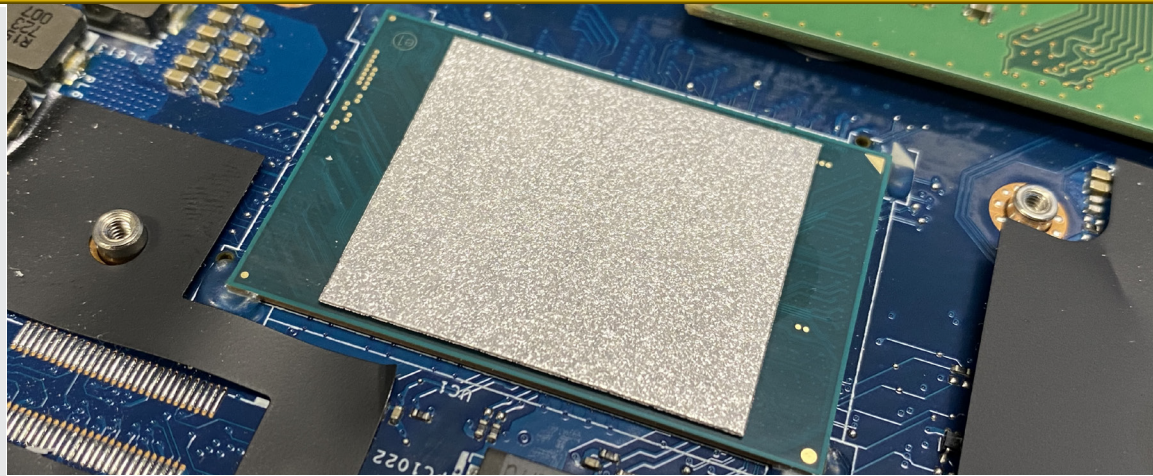
### Custom Die Cut Geometrics Available

#### How to Order Product to Size:

WWWW = Width in inches (ex 5.00" = 0500)  
LLLL = Length in inches (ex 10.00" = 1000)  
TTT = Thickness in inches (ex. 0.040" = 040)

Example: TCF160-05001000-040

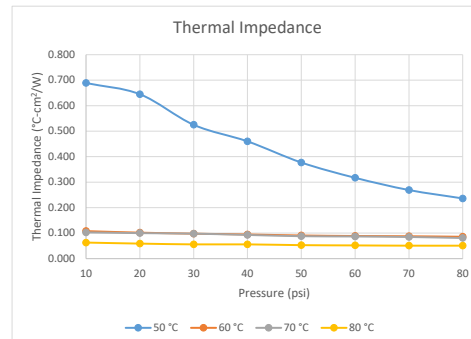
Part numbers will be provided in inches



## TCI Series

Leader Tech's TCI series is a new type of composite indium sheet capable of transitioning from solid to liquid at its melting point and back to solid again at room temperature. Capable of uniform thermal resistance at compressed environments where low stress is applied.

Part Series	Test Method	TCI800
<b>Thermal Properties</b>		
Thermal Conductivity Z axis (W/m-K)	ASTM D 5470	$\geq 80$
Thermal Conductivity X axis (W/m-K), Y axis (W/m-K)	ASTM D 5470	80
Thermal Impedance ( $^{\circ}\text{C}\cdot\text{cm}^2/\text{W}$ ; @50psi)	ASTM D 5470	$\leq 0.04$
<b>Physical Properties</b>		
Color	Visual	Bright Silver
Thickness Range (in, (mm))	ASTM D 374	0.008-0.020 (0.2-0.5)
Width & Length (in, (mm))	N/A	5.91 x 5.91 (150 x 150)
Density (lb/in <sup>3</sup> , (g/cc))	ASTM D 792	0.264 (7.3)
Operating Temperature ( $^{\circ}\text{F}$ ( $^{\circ}\text{C}$ ))	IEC60068-2-14	-58 to 932 (-50 to 500)
Melting Point ( $^{\circ}\text{F}$ ( $^{\circ}\text{C}$ ))	GB/T6 1425-1996	176 (80)
Electrical Resistivity (ohm-m)	GB/T6 146-2010	$8.4 \times 10^{-8}$
Shelf Life (Months)	N/A	12
Compressive Stress % (@50psi)	ASTM D 575	20



Samples size: 25.4mm\*25.4mm, Thickness: 0.25mm

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## ***EMI/RFI Board, Enclosure, Cable Shielding & Thermal Solutions***

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